

CLAIM LISTING

This listing of claims will replace all prior versions, and listings of claims in the application:

IN THE CLAIMS

1. (original) A method of sorting dice by speed comprising:
identifying good and bad dice while the dice are part of a wafer;
making a wafer map of speed grades of the good dice;
dicing the wafer;
for a wafer having first and second speed grades different from each other:
filling an order for a first package type and the first speed grade by
attaching dice of the first speed grade to packages of the first
package type; and
placing dice of the second speed grade into another location; and
completing the process of packaging.
2. (original) The method of sorting dice of Claim 1 wherein the step of placing dice of the second speed grade into another location comprises:
filling an order for a second package type and the second speed grade
by attaching dice of the second speed grade to packages of the
second package type.
3. (original) The method of sorting dice of Claim 1 wherein the step of placing dice of the second speed grade into another location comprises:
placing dice of the second speed grade into a carrier for storage until the
second speed grade is ordered.

4. (original) The method of claim 1 comprising the further step of:
marking each of the packages with a mark indicating the first speed grade.
5. (original) The method of claim 1 wherein the steps of attaching dice are performed by a programmed die attach machine that uses the speed grades in the wafer map.
6. (original) The method of claim 5 wherein the die attach machine further transfers some of the dice to a storage location unpackaged.
7. (original) The method of Claim 5 wherein the die attach machine fills part of an order by attaching dice that have been stored in a storage location to packages of the first package type.
- 8 – 10. (canceled)